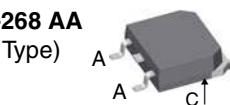
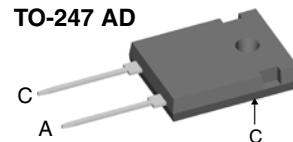
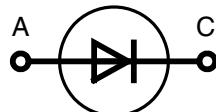


Fast Recovery Epitaxial Diode (FRED)

I_{FAV} = 60 A
V_{RRM} = 600 V
t_{rr} = 35 ms

V _{RSM}	V _{RRM}	Type
V	V	
600	600	DSEI 60-06A
600	600	DSEI 60-06AT



A = Anode, C = Cathode

Symbol	Conditions	Maximum Ratings	
I _{FRMS}		100	A
I _{FAVM} ①	T _C = 70°C; rectangular, d = 0.5	60	A
I _{FRM}	t _p < 10 µs; rep. rating, pulse width limited by T _{VJM}		
I _{FSM}	T _{VJ} = 45°C; t = 10 ms (50 Hz), sine t = 8.3 ms (60 Hz), sine	550 600	A
	T _{VJ} = 150°C; t = 10 ms (50 Hz), sine t = 8.3 ms (60 Hz), sine	480 520	A
I ² t	T _{VJ} = 45°C; t = 10 ms (50 Hz), sine t = 8.3 ms (60 Hz), sine	1510 1490	A ² s
	T _{VJ} = 150°C; t = 10 ms (50 Hz), sine t = 8.3 ms (60 Hz), sine	1150 1120	A ² s
T _{VJ}		-55...+150	°C
T _{VJM}		150	°C
T _{stg}		-55...+150	°C
P _{tot}	T _C = 25°C	166	W
M _d	mounting torque	0.8...1.2	Nm
Weight	typical	6	g

Symbol	Conditions	Characteristic Values		
		typ.	max.	
I _R	V _R = V _{RRM} V _R = 0.8·V _{RRM} V _R = 0.8·V _{RRM}	T _{VJ} = 25°C T _{VJ} = 25°C T _{VJ} = 125°C	200 100 14	µA µA mA
V _F	I _F = 70 A	T _{VJ} = 150°C T _{VJ} = 25°C	1.5 1.8	V V
V _{TO}	For power-loss calculations only		1.13	V
r _T	T _{VJ} = T _{VJM}		4.7	mΩ
R _{thJC}			0.75	K/W
R _{thCH}	(version A)	0.25	0.75	K/W
t _{rr}	I _F = 1 A; -di/dt = 200 A/µs; V _R = 30 V; T _{VJ} = 25°C	35	50	ns
I _{RM}	V _R = 350 V; I _F = 60 A; -di _F /dt = 480 A/µs L ≤ 0.05 µH; T _{VJ} = 100°C	6.0	7.5	A

① I_{FAVM} rating includes reverse blocking losses at T_{VJM}. V_R = 0.8·V_{RRM}, duty cycle d = 0.5

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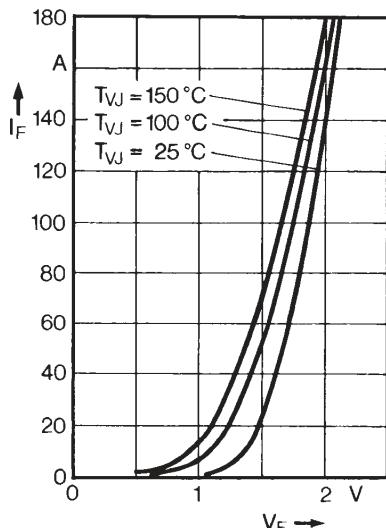


Fig. 1 Forward current versus voltage drop.

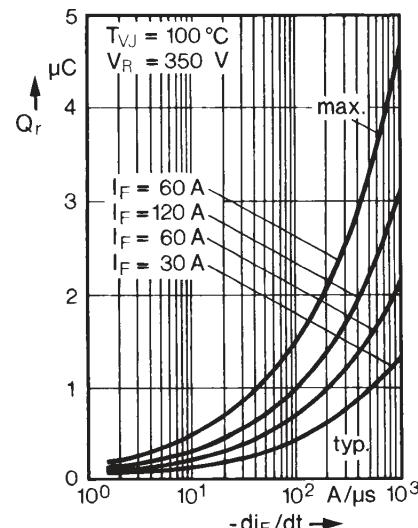


Fig. 2 Recovery charge versus $-di_F/dt$.

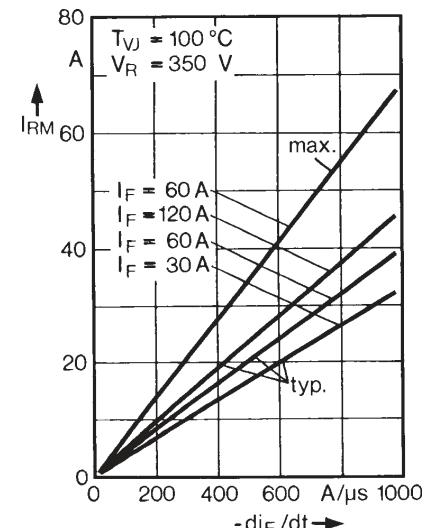


Fig. 3 Peak reverse current versus $-di_F/dt$.

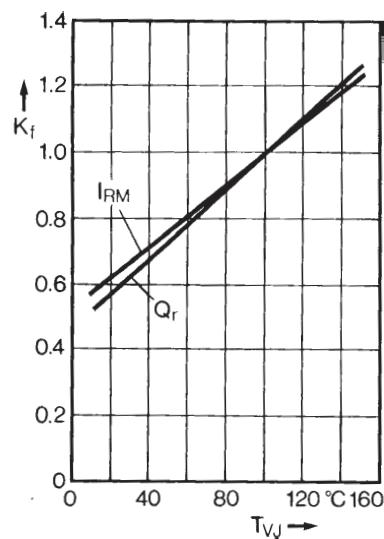


Fig. 4 Dynamic parameters versus junction temperature.

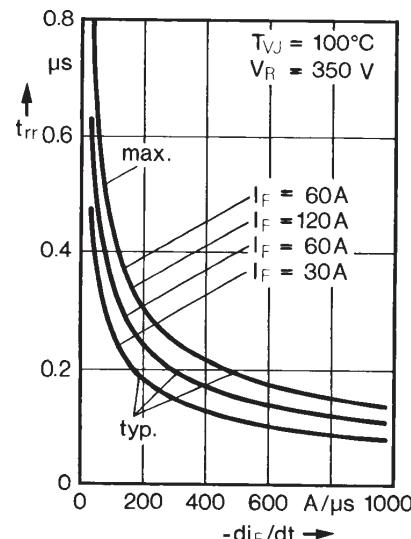


Fig. 5 Recovery time versus $-di_F/dt$.

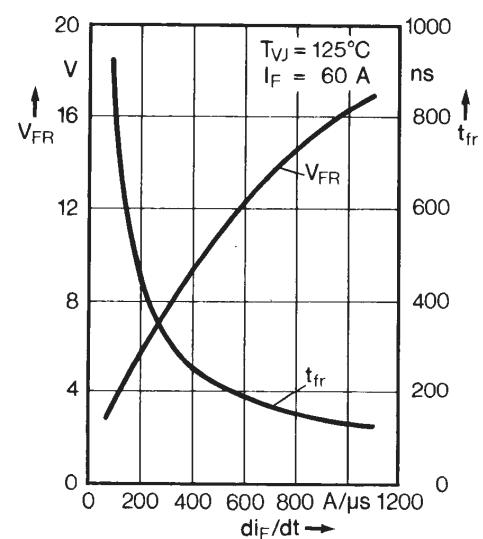


Fig. 6 Peak forward voltage versus di_F/dt .

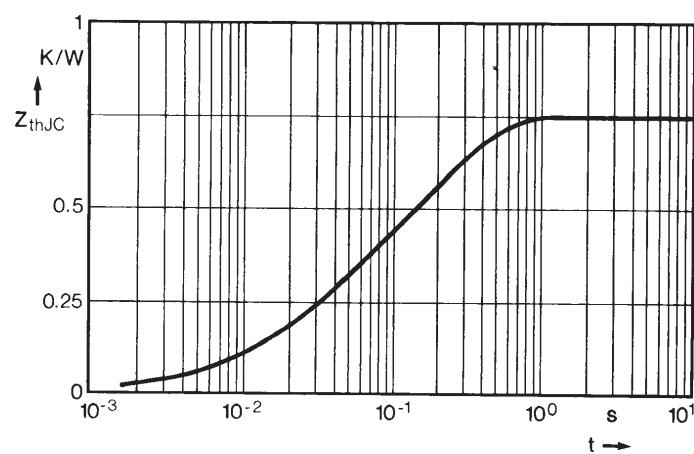
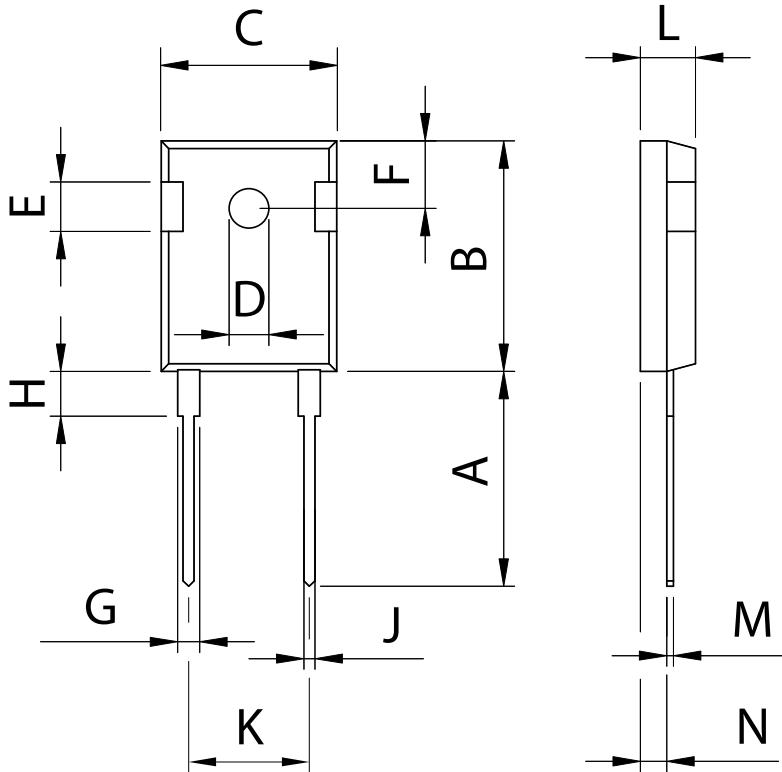


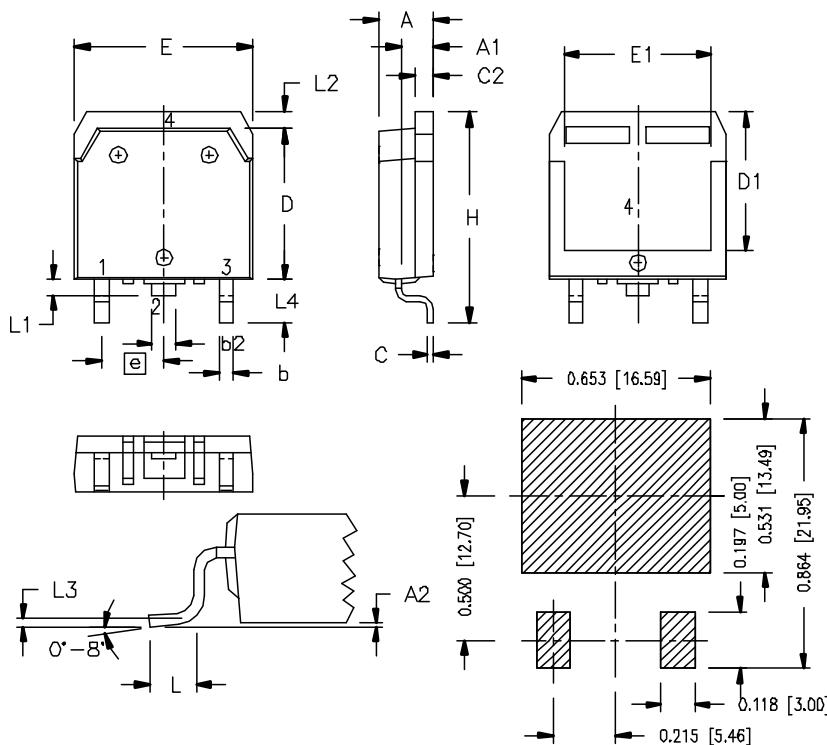
Fig. 7 Transient thermal impedance junction to case.

Dimensions TO-247 AD



Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	19.81	20.32	0.780	0.800
B	20.80	21.46	0.819	0.845
C	15.75	16.26	0.610	0.640
D	3.55	3.65	0.140	0.144
E	4.32	5.49	0.170	0.216
F	5.4	6.2	0.212	0.244
G	1.65	2.13	0.065	0.084
H	-	4.5	-	0.177
J	1.0	1.4	0.040	0.055
K	10.8	11.0	0.426	0.433
L	4.7	5.3	0.185	0.209
M	0.4	0.8	0.016	0.031
N	1.5	2.49	0.087	0.102

Dimensions TO-268 AA



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.193	.201	4.90	5.10
A1	.106	.114	2.70	2.90
A2	.001	.010	0.02	0.25
b	.045	.057	1.15	1.45
b2	.075	.083	1.90	2.10
C	.016	.026	0.40	0.65
C2	.057	.063	1.45	1.60
D	.543	.551	13.80	14.00
D1	.488	.500	12.40	12.70
E	.624	.632	15.85	16.05
E1	.524	.535	13.30	13.60
e	.215	BSC	5.45	BSC
H	.736	.752	18.70	19.10
L	.094	.106	2.40	2.70
L1	.047	.055	1.20	1.40
L2	.039	.045	1.00	1.15
L3	.010	BSC	0.25	BSC
L4	.150	.161	3.80	4.10

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